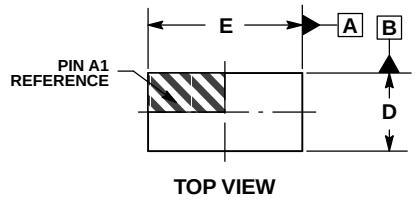
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

ON Semiconductor®

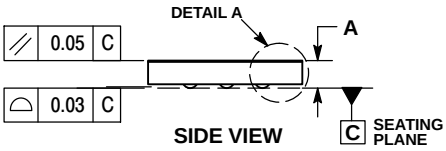
SCALE 4:1

WLCSP6 0.86x1.70x0.265
CASE 567UK
ISSUE A

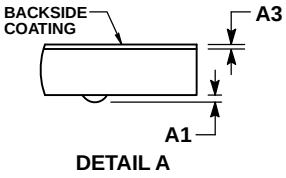
DATE 22 MAY 2017



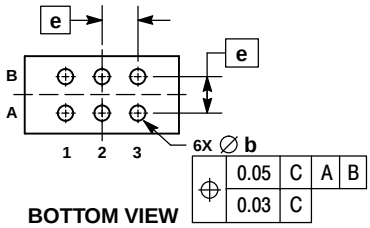
TOP VIEW



SIDE VIEW

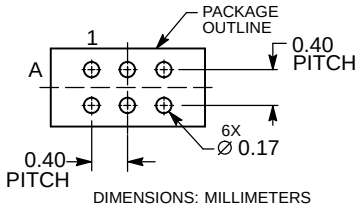


DETAIL A



BOTTOM VIEW

RECOMMENDED SOLDERING FOOTPRINT*



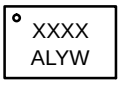
DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF CONTACT BALLS.
4. COPLANARITY APPLIES TO SPHERICAL CROWNS OF CONTACT BALLS.
5. DIMENSION b IS MEASURED AT THE MAXIMUM CONTACT BALL DIAMETER PARALLEL TO DATUM C.

	MILLIMETERS		
DIM	MIN	NOM	MAX
A	0.24	0.265	0.29
A1		0.04 REF	
A3		0.025 REF	
b	0.12	0.17	0.22
D	0.81	0.86	0.91
E	1.65	1.70	1.75
e		0.40 BSC	

GENERIC MARKING DIAGRAM*



A = Assembly Location
L = Wafer Lot
Y = Year
W = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present. Some products may not follow the Generic Marking.

DOCUMENT NUMBER:	**98AON64224G**	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped “CONTROLLED COPY” in red.	
STATUS:	**ON SEMICONDUCTOR STANDARD**		
NEW STANDARD:			
DESCRIPTION:	**WLCSP6 0.86x1.70x0.265**		**PAGE 1 OF 2**

ISSUE	REVISION	DATE
O	RELEASED FOR PRODUCTION. REQ. BY M. MACARAIG.	09 MAY 2017
A	CHANGED TITLE DESCRIPTION TO 0.86x1.70x0.265. REQ. BY M. MACARAIG.	22 MAY 2017